



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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CHEMTRONICS

Technical Data Sheet

TDS # SWick

Soder-Wick® Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® offers the state of the art in desoldering technology. Soder-Wick® is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick® has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Types:	Rosin Grade WW, Type "R" Patented No Clean High Temperature No Clean
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F
No Clean Flux Spec:	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818
Shelflife:	2 years

Size #	Width	Color	Width
	Inches		Metric
1	.030"	White	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm
5	.145"	Brown	3.7mm
6	.210"	Red	5.3mm
BGA	-	Purple	-

STATIC DISSIPATIVE PACKAGING

Soder-Wick® SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick[®] desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks[®] Flux Remover Pen and remove soils with a ControlWipes[™] absorbent wipe.

SODER-WICK[®] IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R
NASA-STD-8739.3
DOD-STD-883E, Method 2022
ANSI/IPC J STD-004, Type ROL0
BELLCORE TR-NWT-000078
ANSI/IPC J SF-818

SODER-WICK[®] SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A
MIL-B-81705C
MIL-STD-1686C
MIL-HDBK-263B

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

AVAILABILITY

Series:

- 40** Soder-Wick[®] Lead-Free, SD Bobbin
- 50** Soder-Wick[®] Rosin
- 80** Soder-Wick[®] Rosin, SD Bobbin
- 60** Soder-Wick[®] No Clean, SD Bobbin
- 70** Soder-Wick[®] Unfluxed
- 75** Soder-Wick[®] Unfluxed, SD Bobbin

VacuPak[™] Packaging

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

HELPFUL HINTS:

Water Soluble Users: Use Soder-Wick[®] Unfluxed **70** or **75** Series to dip in water soluble flux and then desolder normally.

Ball Grid Array: Use Soder-Wick[®] BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

NOTE: This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS[®] does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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